

# GFL 2400 SL

## Gap Filler Liquid

### Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- Low Viscosity Gap Filler Liquid



Properties	Unit	GFL 2400 SL
Colour		green, blue
Basic material		silicone
Mixing ratio		1:1
Curing	°C	90-135 min; 25 °C
<b>Thermal Properties*</b>		
Thermal resistance $R_{th}$	K/W	< 1.02
Thermal conductivity $\lambda$	W/mK	> 2.4
<b>Electrical Properties**</b>		
Dielectric breakdown voltage $U_{d,ac}$	kV	> 7.5
<b>Mechanical Properties</b>		
Hardness	Shore 00	30 - 50
<b>Physical Properties</b>		
Application temperature	°C	-40 to +200
Density	g/cm <sup>3</sup>	2.6
Viscosity	Pas	8 - 20
Total mass loss (TML)	Ma. -%	tbd
Flame rating	UL-94	V-0
Possible thickness	mm	0.2-5.0

\* Measured @ thickness 1mm \*\* Measured @ thickness 0.5 mm